

Applicant: Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn
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Title: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

INFORMATION DISCLOSURE CITATION
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U.S. PATENT DOCUMENTS

Exam Init	Ref	Document Number	Issue Date	Name	Class	Sub Class
<u>TD</u>	_____	US 6,294,838 B1	9/25/2001	Peng		

FOREIGN PATENT DOCUMENTS

Exam Init	Ref	Document Number	Publication Date	Country	Name
<u>TD</u>	_____	2002-43395	6/10/2002	Korea	Eun-Yeong Jung
<u>TD</u>	_____	2002-36191	5/16/2002	Korea	Beak, et al.

OTHER DOCUMENTS

Exam Init	Ref	Author, Title, Date, Pertinent Pages, Etc.)
<u>TD</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-43395 published 6/10/2002.
<u>TD</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-36191, published 5/16/2002.

Examiner: Thompson

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